| ASSOCIATION CONNECTING LECTRONICS INDUSTRIES® INDUSTRIES® INTERNATIONALS INDUSTRIES® | PC. Bannockl | burn. Illinois. A | Ill rights reserved untions. | under both | This docum level parts, t | ent is a declarat | ion of the spencompasse | ubstances s all lowe | within the ma r level materi | anufacture als for whi | r listed item. ich the manuf | Note: if t acturer h | he item is an as as engineering | sembly with lower responsibility. | |
|---|--|-------------------|------------------------------|----------------------|---|--|--|-------------------------|---------------------------------|-------------------------------------|---------------------------------|-------------------------|------------------------------------|--------------------------------------|--|
| | IPC Web Site for Information on IPC-1752 Standard Fo http://www.ipc.org/IPC-175x Dis | | | | Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater | | | | | is Material | ials and Mfg Information | | | | |
| Supplier Information | | | | | | | | | | | | | | | |
| Company name* | Company un | Company unique ID | | | Unique ID Authority | | | | | Response Date* | | | | | |
| onsemi | | | | | | | | | | | 2024-05-19 | | | | |
| Contact Name Title - Con | | | - Contact | | | Phone - Contact* | | | | | Email - Contact* | | | | |
| Product-Env-Stewards Produ | | | Product Enviro Compliance | | | NA | | | | | Product-Env-Stewards@onsemi.com | | | | |
| Authorized Representative* Title - | | | tle - Representative | | | Phone - Representative* | | | | 1 | Email - Representative* | | | | |
| Product-Env-Stewards Product | | | roduct Enviro Compliance | | | NA | | | | | Product-Env-Stewards@onsemi.com | | | | |
| Requester Item Number | Mfr Iten | n Number | Mfr Item Name | | | Effective Date Version Manufacturing Sit | | g Site | Weig | ht* | UOM | Unit Type | | | |
| | MOC302 | 21SVM | 6PW RP TRIAC SMD VDE | | 2024-05-19 | | | ТНН | | 464.9 | 03 | mg | Each | | |
| Manufacturing Proccess Informa | tion | | | | | | | | | | | | | | |
| Terminal Plating / Grid Array M | Array Material Terminal Base | | Alloy | J-STD-020 MSL Rating | | Peak Proc | Process Body Temperature Max Time at Pea | | e at Peak T | Temperature Number of Reflow Cycles | | | | | |
| Matte Tin (Sn) - annealed CU Allo | | CU Alloy | 1 | | | 260 | 260 C 30 | | | seconds 3 | | | | | |
| Comments | | | | | | | | | | | | | | | |
| evel 1 - maximum time at peak temperat | ire during so | ldering is 10-3 | 0 seconds | | | | | | | | | | | | |
| or more information regarding material | composition | please refer to | page 3 | | | | | | | | | | | | |

| RoHS Material Composition Declaration | | | | Declaration Type * | Detailed | | | | | | | |
|--|--|---|---|---|---|--|--|--|--|--|--|--|
| Directive 2015/863/EU amending RoHS Directive 2011/65/EU | (Pb), Mercury (Hg), Hexavalent Chror | oHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead b), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl thalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP). | | | | | | | | | | |
| cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a | ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the | henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies | RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform | ce of its products with European Union membe | ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of | | | | | | | |
| RoHS Declaration * 1 - Item(s) | does not contain RoHS restricted substa | on above | Supplier Acceptance | * Accepted | | | | | | | | |
| Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions. | | | | | | | | | | | | |
| Exemption List Version | EL-2011/534/EU | | | | | | | | | | | |
| Declaration Signature | | | | | | | | | | | | |
| Instructions: Complete all of the required fin Requester) and click on Submit Form to have | elds on all pages of this form. Select the form returned to the Requester | he "Accepted" on th | e Supplier Acceptance drop-down | . This will display the signature area. Digital | lly sign the declaration (if required by the | | | | | | | |
| Supplier Digital Signature Ra | stislav Drska | Le | | | | | | | | | | |

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

| Homogeneous Material | Weight | Unit of Measure | Level | Substance | CAS | Exempt | Weight | Unit of Measure |
|----------------------|---------|-----------------|----------|---|------------|--------|---------|-----------------|
| Coupling Gel | 0.4 | mg | Supplier | Dimethyl Cyclosiloxanes | 69430-24-6 | | 0.04 | mg |
| | | | Supplier | Trimethoxy(methyl)silane (C4H12O3Si) | 1185-55-3 | | 0.36 | mg |
| Die | 5.13 | mg | Supplier | Silicon (Si) | 7440-21-3 | | 5.13 | mg |
| Die Attach | 0.3 | mg | Supplier | Silver (Ag) | 7440-22-4 | | 0.225 | mg |
| | | | Supplier | Phenolic Resin-2 | 54208-63-8 | | 0.075 | mg |
| Lead Frame 10 | 101.703 | mg | Supplier | Silver (Ag) | 7440-22-4 | | 0.407 | mg |
| | | | Supplier | Zinc (Zn) | 7440-66-6 | | 0.203 | mg |
| | | | Supplier | Iron (Fe) | 7439-89-6 | | 2.64 | mg |
| | | | Supplier | Copper (Cu) | 7440-50-8 | | 98.3 | mg |
| | | | Supplier | Phosphorus (P) | 7723-14-0 | | 0.153 | mg |
| Mold Compound-White | 327.22 | mg | Supplier | Titanium Dioxide (TiO2) | 13463-67-7 | | 81.805 | mg |
| | | | В | Brominated Bisphenol A Diglycidyl Ether | 40039-93-8 | | 9.8166 | mg |
| | | | Supplier | Ortho Cresol Novolac Resin | 29690-82-2 | | 44.1747 | mg |
| | | | В | Antimony Trioxide (Sb2O3) | 1309-64-4 | | 9.8166 | mg |
| | | | Supplier | Fused Silica (SiO2) | 60676-86-0 | | 163.61 | mg |
| | | | Supplier | Phenolic Resin (Novolac) | 9003-35-4 | | 17.9971 | mg |
| Plating | 28.5 | mg | Supplier | Tin (Sn) | 7440-31-5 | | 28.5 | mg |
| Wire Bond - Au | 1.65 | mg | Supplier | Gold (Au) | 7440-57-5 | | 1.65 | mg |